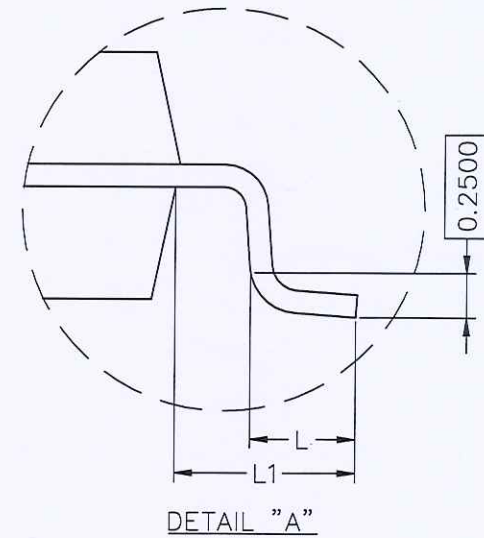


	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	-	-	1.60
STAND OFF	A1	0.05	0.10	0.15
MOLD TOTAL THICKNESS	A2	1.35	1.40	1.45
TOP MOLD THICKNESS	A3	0.59	0.64	0.69
LEAD WIDTH	b	0.18	0.20	0.26
LEAD WIDTH	b1	0.17	0.20	0.23
LEAD THICKNESS	c	0.13	-	0.17
LEAD THICKNESS	c1	0.12	0.13	0.14
LEAD SPAN (X)	D	11.80	12.00	12.20
MOLD LENGTH (X)	D1	9.90	10.00	10.10
LEAD SPAN (Y)	E	11.80	12.00	12.2
MOLD WIDTH (Y)	E1	9.90	10.00	10.10
LEAD PITCH	e	0.50 BSC		
LEAD SOLE LENGTH	L	0.45	0.60	0.75
LEAD LENGTH	L1	1.00 REF		
LEAD FORM ANGLE	θ	0°	-	7°



A	INITIAL ISSUE				Huangyiwei		2021/08/15	
REV	DESCRIPTION OF CHANGE				DRAWER		ISSUE DATE	
TITLE	LQFP64(10x10) POD				气派科技 chippacking			
DWG No.	C-OL-154	MATERIAL						
X	±0.5	REV	A	SHEET	1/1	DWN	Huangyiwei	
X.X	±0.1			SCALE	NOTS	CKD	2021/08/15	
X.XX	±0.05			UNIT	MM	APPD		
X.XXX	±0.050							